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Our Case No. 9651/4017
Client Reference No. FT US99005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Hitoshi Seki et al.

Serial No.: ~~To Be Assigned~~ 09/595415

Filing Date: ~~Herewith~~ 6-16-00

For Etching Reagent, And Method For
Manufacturing Electronic Device
Substrate And Electronic Device

BEST AVAILABLE COPY

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Prior to examination of the above-identified application, please amend the application as follows:

In the Specification

On page 4, line 3 delete "a" and substitute --an--;

On page 4, line 17 delete "amount" and substitute --amounts--;

On page 5, line 18 delete "rapid etching rate" and substitute --rapidly etched--;

On page 5, line 22 delete "that" and substitute --and--;

On page 9, line 6 delete "Since the" and substitute --The--;

On page 27, line 7 delete "an";

On page 27, line 7 after "rate" insert --as--;

On page 28, line 24 delete "an";

On page 28, last line delete "by" and substitute --in--; and

On page 46, line 5 delete "yesy piexe" and substitute --test piece--.